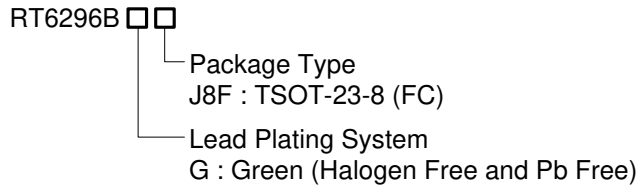


## 2A, 17V Current Mode Synchronous Step-Down Converter

### General Description

The RT6296B is a high-efficiency, 2A current mode synchronous step-down DC-DC converter with a wide input voltage range from 4.5V to 17V. The device integrates 100mΩ high-side and 40mΩ low-side MOSFETs to achieve high efficiency conversion. The current mode control architecture supports fast transient response and internal compensation. A cycle-by-cycle current limit function provides protection against shorted output. The RT6296B provides complete protection functions such as input under-voltage lockout, output under-voltage protection, over-current protection, and thermal shutdown. The PWM frequency is adjustable by the EN/SYNC pin. The RT6296B is available in the TSOT-23-8 (FC) package.

### Ordering Information



Note :

Richtek products are :

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

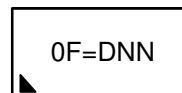
### Features

- 4.5V to 17V Input Voltage Range
- 2A Output Current
- Internal N-Channel MOSFETs
- Current Mode Control
- Fixed Switching Frequency : 500kHz
- Synchronous to External Clock : 200kHz to 2MHz
- Cycle-by-Cycle Current Limit
- External Soft-Start Function
- Input Under-Voltage Lockout
- Output Under-Voltage Protection
- Thermal Shutdown

### Applications

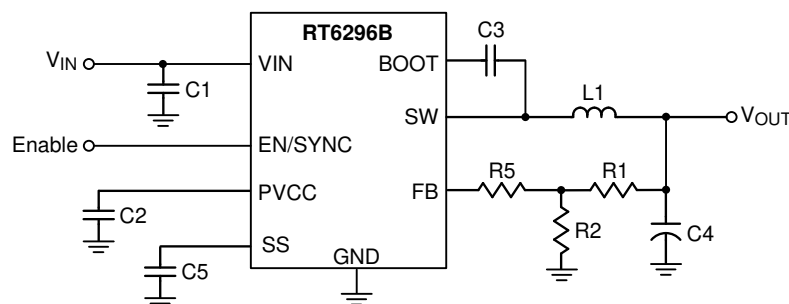
- Industrial and Commercial Low Power Systems
- Computer Peripherals
- LCD Monitors and TVs
- Set-top Boxes

### Marking Information



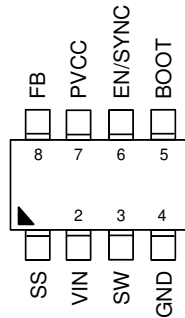
0F= : Product Code  
DNN : Date Code

### Simplified Application Circuit



## Pin Configuration

(TOP VIEW)

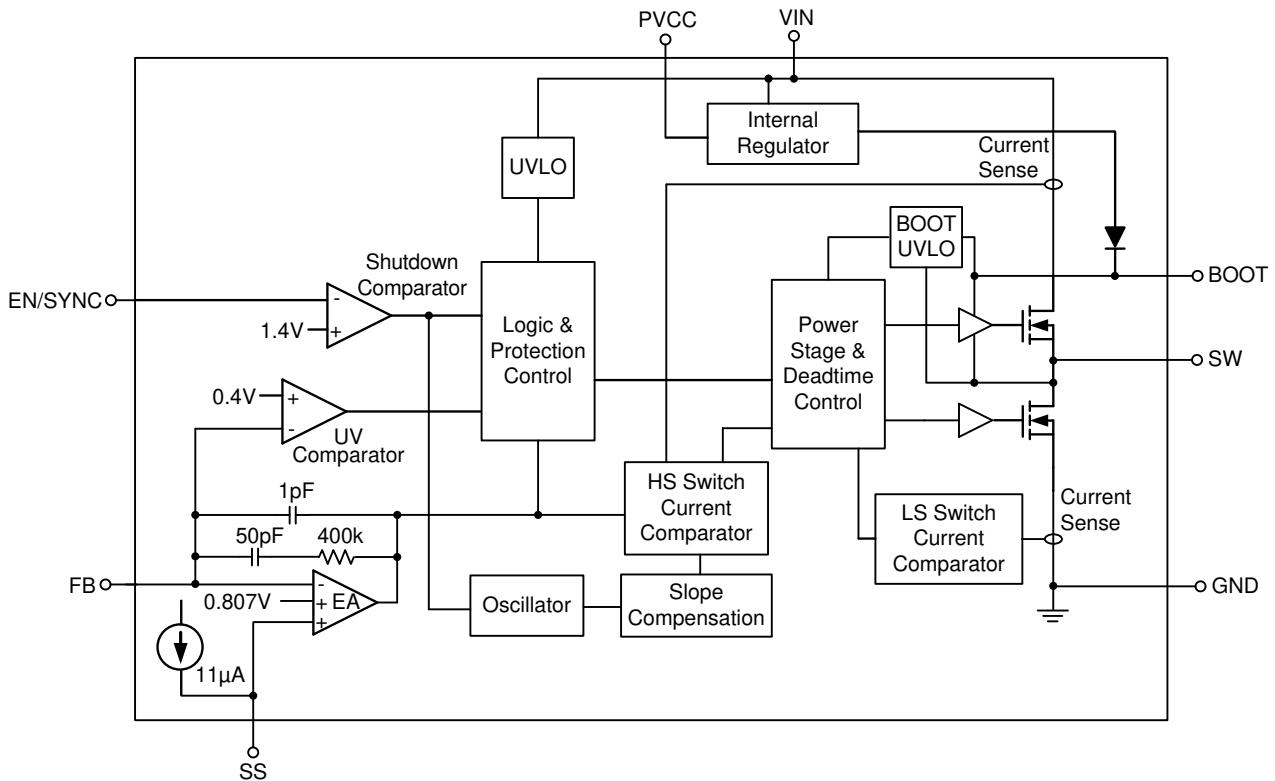


TSOT-23-8 (FC)

## Functional Pin Description

Pin No.	Pin Name	Pin Function
1	SS	Soft-start control input. SS control the soft-start period. Connect a capacitor from SS to GND to set the soft-start period.
2	VIN	Power input. Support 4.5V to 17V Input Voltage. Must bypass with a ceramic capacitor at this pin.
3	SW	Switch node. Connect to external L-C filter.
4	GND	System ground.
5	BOOT	Bootstrap supply for high-side gate driver. Connect a 0.1μF ceramic capacitor between the BOOT and SW pins.
6	EN/SYNC	Enable control input. High = Enable. Apply an external clock to adjust the switching frequency. If using pull high resistor connected to VIN, the recommended value range is 60kΩ to 300kΩ.
7	PVCC	5V bias supply output. Connect a minimum of 0.1μF capacitor to ground.
8	FB	Feedback voltage input. The pin is used to set the output voltage of the converter to regulate to the desired voltage via a resistive divider. Feedback reference = 0.807V.

Functional Block Diagram



Operation

Under Voltage Lockout Threshold

The IC includes an input Under Voltage Lockout Protection (UVLO). If the input voltage exceeds the UVLO rising threshold voltage (3.9V), the converter resets and prepares the PWM for operation. If the input voltage falls below the UVLO falling threshold voltage (3.25V) during normal operation, the device stops switching. The UVLO rising and falling threshold voltage includes a hysteresis to prevent noise caused reset.

Chip Enable

The EN pin is the chip enable input. Pulling the EN pin low (<1.1V) will disable the device. During shutdown mode (<0.4V), the RT6296B's quiescent current drops to lower than 1µA. Driving the EN pin high (>1.6V) will turn on the device.

Operating Frequency and Synchronization

The internal oscillator runs at 500kHz (typ.) when the EN/SYNC pin is at logic-high level (>1.6V). If the EN

pin is pulled to low-level over 8µs, the IC will shut down. The RT6296B can be synchronized with an external clock ranging from 200kHz to 2MHz applied to the EN/SYNC pin. The external clock duty cycle must be from 20% to 80% with logic-high level = 2V and logic-low level = 0.8V.

Internal Regulator

The internal regulator generates 5V power and drive internal circuit. When VIN is below 5V, PVCC will drop with VIN. A capacitor(>0.1µF) between PVCC and GND is required.

External Soft-Start Function

The RT6296B provides external soft-start function. The soft-start function is used to prevent large inrush current while converter is being powered-up. The soft-start timing can be programmed by the external capacitor between SS pin and GND. The Chip provides a 11µA charge current for the external capacitor 100µs after EN rising. As shown in Figure 1, output voltage starts to rise after 0.4 x t<sub>SS</sub>.

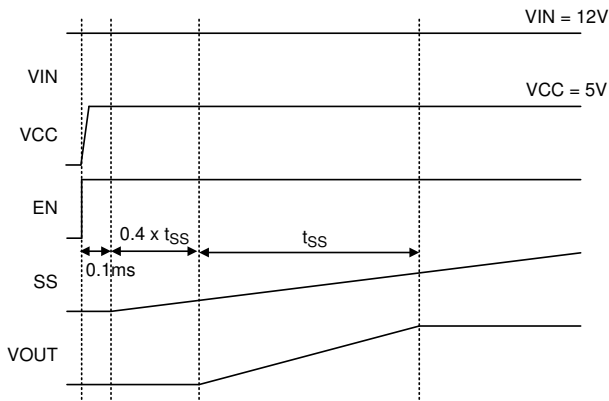


Figure. 1 Start-Up Sequence

**High-Side MOSFET Over-Current Limit**

The RT6296B features cycle-by-cycle current-limit protection and prevents the device from the catastrophic damage in output short circuit, over current or inductor saturation. During the on-time of the high side switch, the device monitors the switch current. If the switch current overs the current limit threshold, the device turns off the high side switch to prevent the device from damage.

**Output Under-Voltage Protection**

The RT6296B includes output under-voltage protection (UVP) against over-load or short-circuited condition by

constantly monitoring the feedback voltage  $V_{FB}$ . If  $V_{FB}$  drops below the under-voltage protection trip threshold, 50% (typ.) of the internal reference voltage, the UV comparator will go high to turn off the internal high-side MOSFET switches. If the output under-voltage condition continues for a period of time, the RT6296B will enter output under-voltage protection with hiccup mode. During hiccup mode, the device remains shut down. After a period of time, a soft-start sequence for auto-recovery will be initiated. Upon completion of the soft-start sequence, if the fault condition is removed, the converter will resume normal operation; otherwise, such cycle for auto-recovery will be repeated until the fault condition is cleared. Hiccup mode allows the circuit to operate safely with low input current and power dissipation, and then resume normal operation as soon as the over-load or short-circuit condition is removed. The UVP profile is shown in Figure 2.

**Thermal Shutdown**

Thermal shutdown is implemented to prevent the chip from operating at excessively high temperatures. When the junction temperature is higher than 150°C, the chip will shutdown the switching operation. The chip is automatically re-enabled when the junction temperature cools down by approximately 20°C.

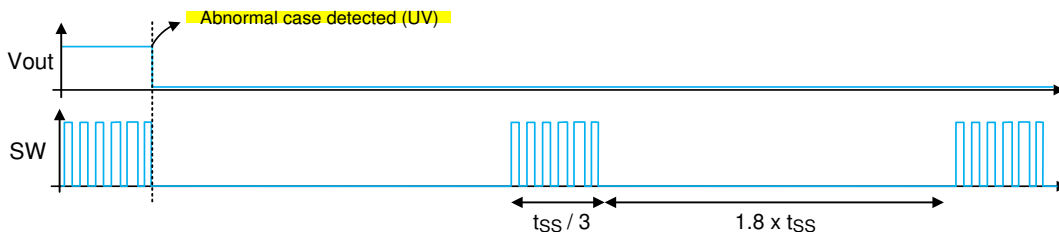


Figure. 2 Output Under-Voltage Protection with Hiccup Mode

**Absolute Maximum Ratings** (Note 1)

- Supply Input Voltage,  $V_{IN}$  ----- -0.3V to 20V
- Switch Voltage,  $SW$ ----- -0.3V to  $V_{IN} + 0.3V$   
 $<20ns$ ----- -5V
- BOOT to SW,  $V_{BOOT} - SW$  ----- -0.3V to 6V (7V for  $< 10\mu s$ )
- Bias Supply Output,  $PVCC$ ----- -0.3V to 6V (7V for  $< 10\mu s$ )
- Other Pins----- -0.3V to 6V
- Power Dissipation,  $P_D @ T_A = 25^\circ C$   
 TSOT-23-8 (FC)----- 1.428W
- Package Thermal Resistance (Note 2)  
 TSOT-23-8 (FC),  $\theta_{JA}$  ----- 70°C/W  
 TSOT-23-8 (FC),  $\theta_{JC}$  ----- 15°C/W
- Lead Temperature (Soldering, 10 sec.)----- 260°C
- Junction Temperature----- -40°C to 150°C
- Storage Temperature Range ----- -65°C to 150°C
- ESD Susceptibility (Note 3)  
 HBM (Human Body Model) ----- 2kV

**Recommended Operating Conditions** (Note 4)

- Supply Input Voltage,  $V_{IN}$ ----- 4.5V to 17V
- Junction Temperature Range ----- -40°C to 125°C
- Ambient Temperature Range ----- -40°C to 85°C

**Electrical Characteristics**

( $V_{IN} = 12V$ ,  $T_A = 25^\circ C$ , unless otherwise specified)

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Shutdown Supply Current			$V_{EN} = 0V$	--	--	1	$\mu A$
Quiescent Current with no Load at DCDC Output			$V_{EN} = 2V, V_{FB} = 1V$	--	0.8	1	mA
Feedback Voltage		$V_{FB}$		0.799	0.807	0.815	V
Feedback Current		$I_{FB}$	$V_{FB} = 820mV$	--	10	50	nA
Switch On-Resistance	High-Side	$R_{DS(ON)H}$		--	100	--	m $\Omega$
	Low-Side	$R_{DS(ON)L}$		--	40	--	
Switch Leakage			$V_{EN} = 0V, V_{SW} = 0V$	--	--	1	$\mu A$
Current Limit		$I_{LIM}$	Under 40% duty-cycle	3	4	4.6	A
Low-Side Switch Current Limit			From drain to source	--	2	--	A
Oscillation Frequency		$f_{OSC}$	$V_{FB} = 0.75V$	440	500	580	kHz
SYNC Frequency Range		$f_{SYNC}$		200	--	2000	kHz
Fold-Back Frequency			$V_{FB} < 400mV$	--	125	--	kHz
Maximum Duty-Cycle		$D_{MAX}$	$V_{FB} = 0.7V$	90	95	--	%

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Minimum On-Time		t <sub>ON</sub>		--	60	--	ns
EN Input Voltage	Logic-High	V <sub>IH</sub>		1.2	1.4	1.6	V
	Logic-Low	V <sub>IL</sub>		1.1	1.25	1.4	
EN Input Current		I <sub>EN</sub>	V <sub>EN</sub> = 2V	--	2	--	μA
			V <sub>EN</sub> = 0V	--	0	--	
EN Turn-off Delay		EN <sub>td-off</sub>		--	8	--	μs
Input Under-Voltage Lockout Threshold	V <sub>IN</sub> Rising	V <sub>UVLO</sub>	V <sub>IN</sub> rising	3.7	3.9	4.1	V
	Hysteresis	ΔV <sub>UVLO</sub>		--	650	--	mV
VCC Regulator		V <sub>CC</sub>		--	5	--	V
VCC Load Regulation		ΔV <sub>LOAD</sub>	I <sub>VCC</sub> = 5mA	--	3	--	%
Soft-Start Charge Current		I <sub>SS</sub>		--	11	--	μA
Thermal Shutdown Temperature		T <sub>SD</sub>		--	150	--	°C
Thermal Shutdown Hysteresis		ΔT <sub>SD</sub>		--	20	--	°C

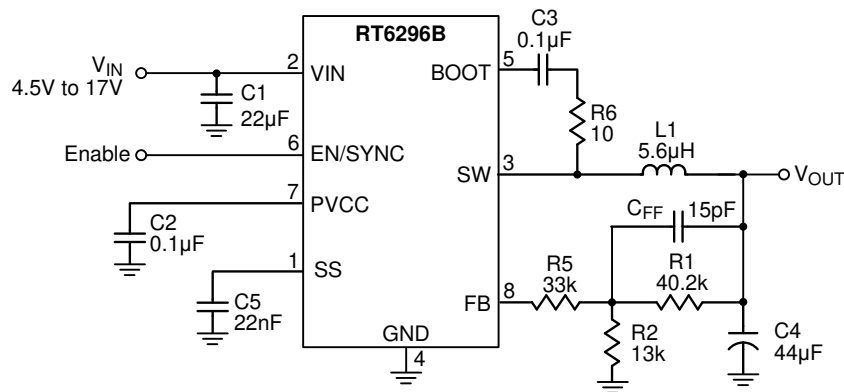
**Note 1.** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

**Note 2.** θ<sub>JA</sub> is measured at T<sub>A</sub> = 25°C on a high effective thermal conductivity four-layer test board per JEDEC 51-7. θ<sub>JC</sub> is measured at the exposed pad of the package.

**Note 3.** Devices are ESD sensitive. Handling precaution recommended.

**Note 4.** The device is not guaranteed to function outside its operating conditions.

**Typical Application Circuit**

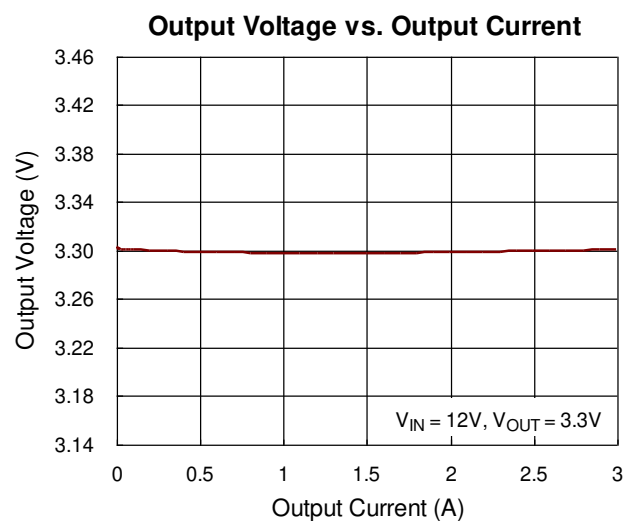
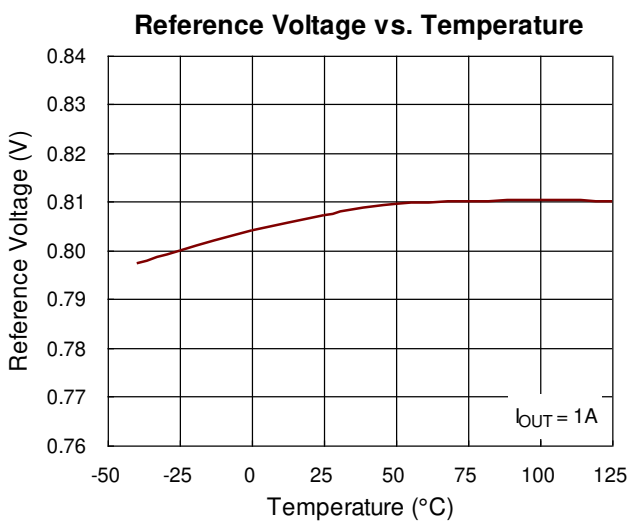
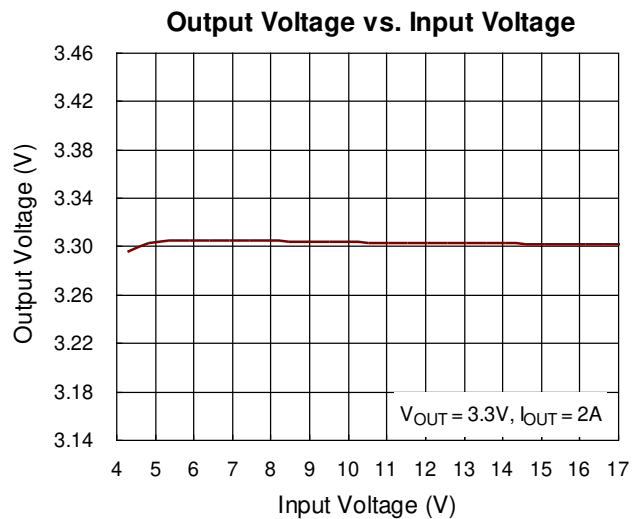
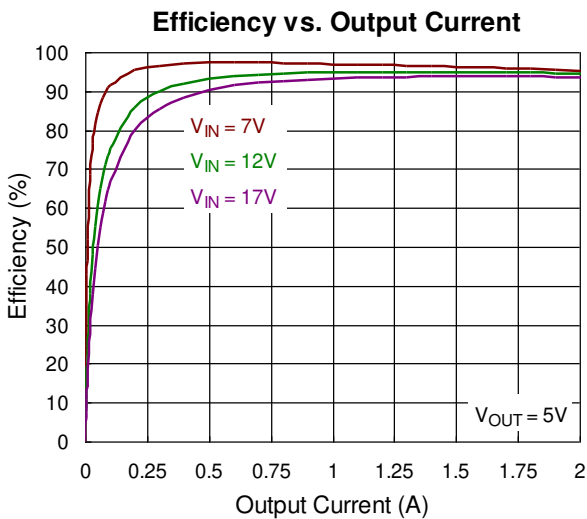
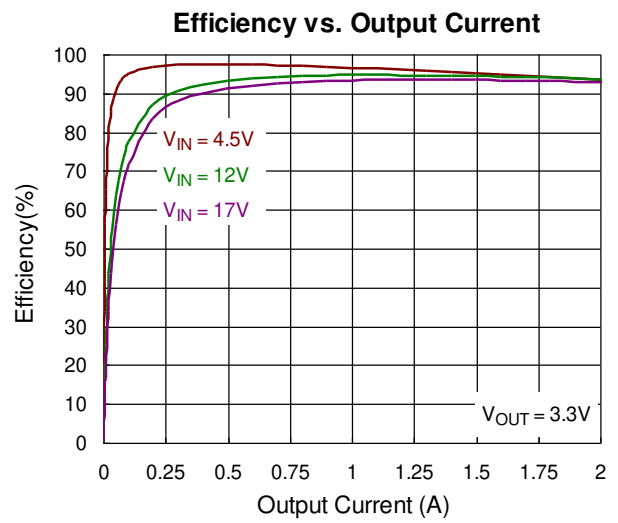
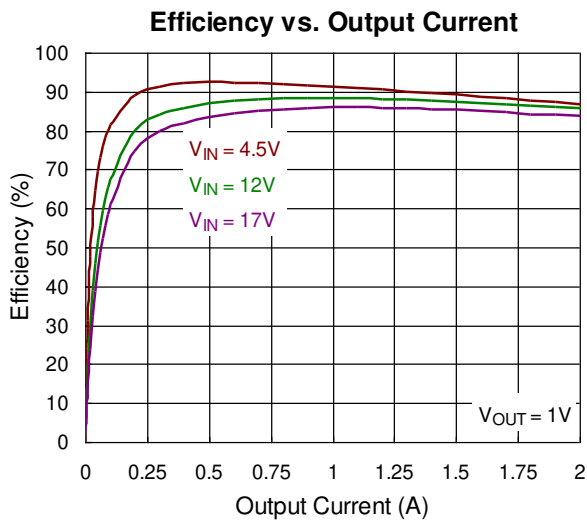


**Table 1. Suggested Component Values**

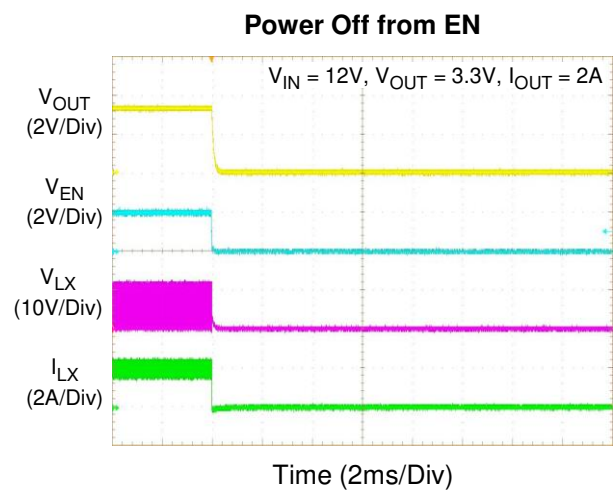
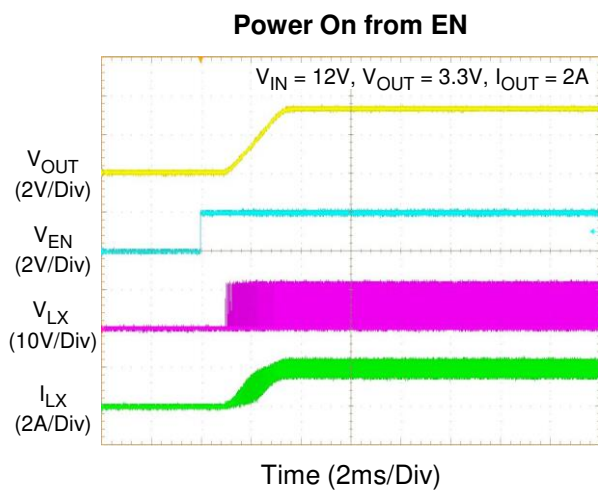
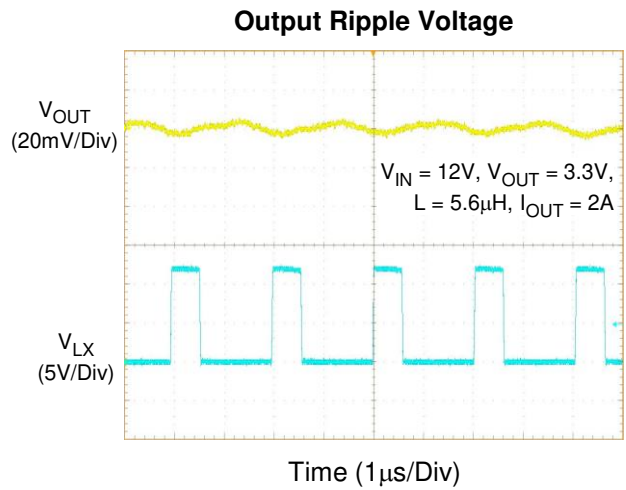
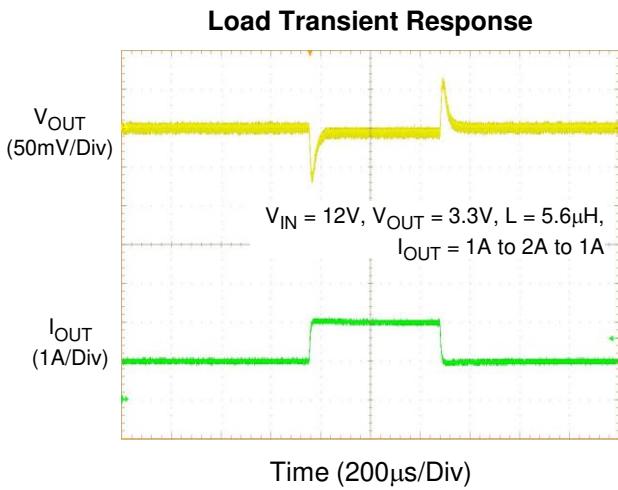
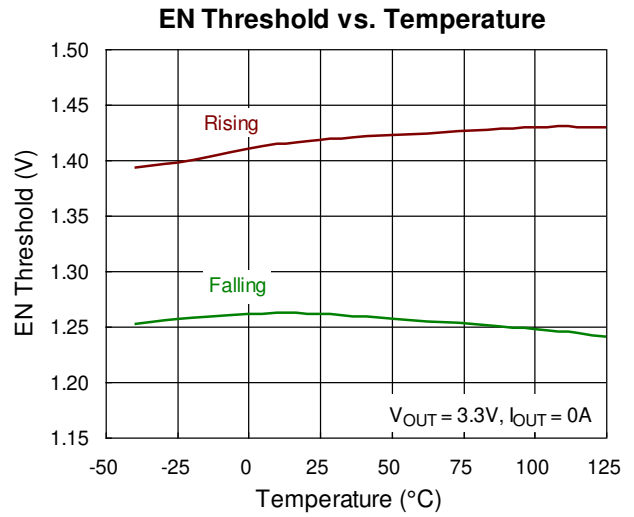
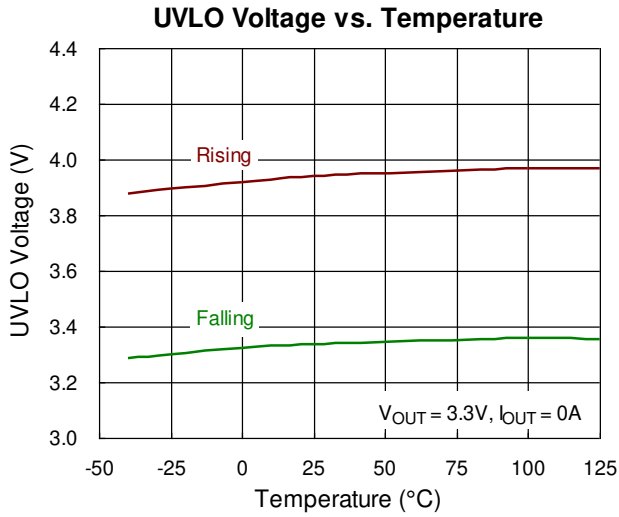
V <sub>OUT</sub> (V)	R1 (kΩ)	R2 (kΩ)	R5 (kΩ)	C <sub>FF</sub> (pF)	C4 (µF)	L1 (µH)
1.0	20.5	84.5	82	15	44	2.2
3.3	40.2	13	33	15	44	5.6
5.0	40.2	7.68	33	15	44	5.6

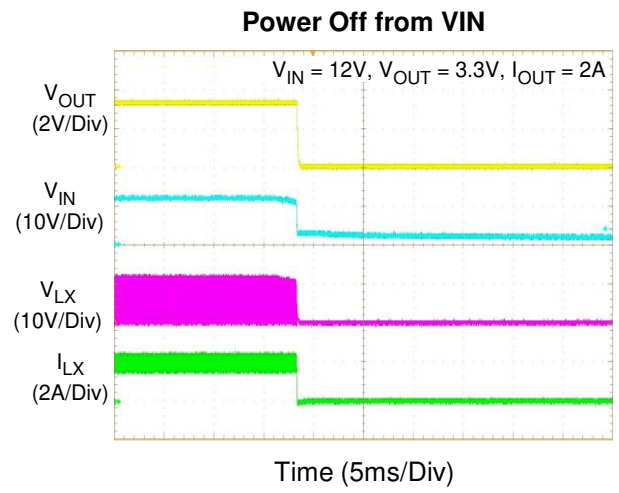
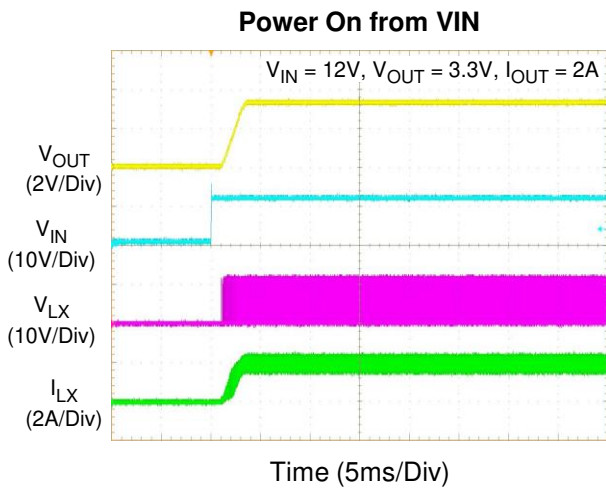
Note : Where the C4 value means the effective output capacitance. Design engineer must be aware that ceramic capacitance varies a great deal with the size, operating voltage and temperature. The variation should be taken into the design consideration of control loop bandwidth. A rule-of-the-thumb is to design the RT6296B control loop bandwidth below 60kHz by changing the value of R5. Generally, increase the value of R5 if a de-rated capacitance is used.

Typical Operating Characteristics









### Application Information

The RT6296B is a high voltage buck converter that can support the input voltage range from 4.5V to 17V and the input voltage range from 4.5V to 17V and the output current can be up to 2A.

#### Output Voltage Selection

The resistive voltage divider allows the FB pin to sense a fraction of the output voltage as shown in Figure 3.

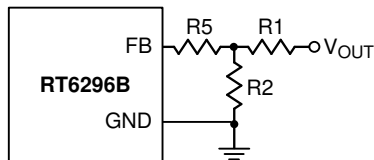


Figure 3. Output Voltage Setting

For adjustable voltage mode, the output voltage is set by an external resistive voltage divider according to the following equation :

$$V_{OUT} = V_{FB} \left( 1 + \frac{R1}{R2} \right)$$

Where  $V_{FB}$  is the feedback reference voltage (0.807V typ.). Table 1 lists the recommended resistors value for common output voltages.

Table 2. Recommended Resistors Value

V <sub>OUT</sub> (V)	R1 (kΩ)	R2 (kΩ)	R5 (kΩ)
1.0	20.5	84.5	82
3.3	40.2	13	33
5.0	40.2	7.68	33

#### External Bootstrap Diode

Connect a 100nF low ESR ceramic capacitor between the BOOT pin and SW pin. This capacitor provides the gate driver voltage for the high side MOSFET. It is recommended to add an external bootstrap diode between an external 5V and BOOT pin, as shown as Figure 4, for efficiency improvement when input voltage is lower than 5.5V or duty ratio is higher than 65%. The bootstrap diode can be a low cost one such as IN4148 or BAT54. The external 5V can be a 5V fixed input from system or a 5V output (PVCC) of the RT6296B.

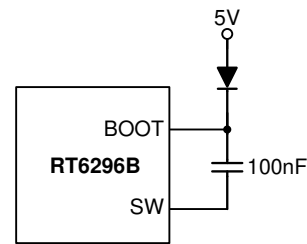


Figure 4. External Bootstrap Diode

#### External Soft-Start Capacitor

The RT6296B provides external soft-start function. The soft-start function is used to prevent large inrush current while converter is being powered-up. The soft-start timing can be programmed by the external capacitor ( $C_{SS}$ ) between SS pin and GND. The Chip provides a 11μA charge current ( $I_{SS}$ ) for the external capacitor. The soft-start time ( $t_{SS}$ ,  $V_{REF}$  is from 0V to 0.8V) can be calculated by the following formula :

$$t_{SS}(ms) = \frac{C_{SS}(nF) \times 1.3}{I_{SS}(\mu A)}$$

#### Inductor Selection

The inductor value and operating frequency determine the ripple current according to a specific input and output voltage. The ripple current  $\Delta I_L$  increases with higher  $V_{IN}$  and decreases with higher inductance.

$$\Delta I_L = \left( \frac{V_{OUT}}{f \times L} \right) \times \left( 1 - \frac{V_{OUT}}{V_{IN}} \right)$$

Having a lower ripple current reduces not only the ESR losses in the output capacitors but also the output voltage ripple. High frequency with small ripple current can achieve highest efficiency operation. However, it requires a large inductor to achieve this goal.

For the ripple current selection, the value of  $\Delta I_L = 0.3(I_{MAX})$  will be a reasonable starting point. The largest ripple current occurs at the highest  $V_{IN}$ . To guarantee that the ripple current stays below the specified maximum, the inductor value should be chosen according to the following equation :

$$L = \left( \frac{V_{OUT}}{f \times \Delta I_L(MAX)} \right) \times \left( 1 - \frac{V_{OUT}}{V_{IN(MAX)}} \right)$$

The inductor's current rating (caused a 40°C temperature rising from 25°C ambient) should be greater than the maximum load current and its saturation current should be greater than the short circuit peak current limit.

### C<sub>IN</sub> and C<sub>OUT</sub> Selection

The input capacitance, C<sub>IN</sub>, is needed to filter the trapezoidal current at the source of the top MOSFET. To prevent large ripple current, a low ESR input capacitor sized for the maximum RMS current should be used. The RMS current is given by :

$$I_{RMS} = I_{OUT(MAX)} \frac{V_{OUT}}{V_{IN}} \sqrt{\frac{V_{IN}}{V_{OUT}} - 1}$$

This formula has a maximum at V<sub>IN</sub> = 2V<sub>OUT</sub>, where I<sub>RMS</sub> = I<sub>OUT</sub>/2. This simple worst-case condition is commonly used for design because even significant deviations do not offer much relief.

Choose a capacitor rated at a higher temperature than required. Several capacitors may also be paralleled to meet size or height requirements in the design. The selection of C<sub>OUT</sub> is determined by the required Effective Series Resistance (ESR) to minimize voltage ripple. Moreover, the amount of bulk capacitance is also a key for C<sub>OUT</sub> selection to ensure that the control loop is stable. Loop stability can be checked by viewing the load transient response as described in a later section. The output ripple, ΔV<sub>OUT</sub>, is determined by :

$$\Delta V_{OUT} \leq \Delta I_L \times \left( ESR + \frac{1}{8fC_{OUT}} \right)$$

The output ripple will be highest at the maximum input voltage since ΔI<sub>L</sub> increases with input voltage. Multiple capacitors placed in parallel may be needed to meet the ESR and RMS current handling requirement. Dry tantalum, special polymer, aluminum electrolytic and ceramic capacitors are all available in surface mount packages. Special polymer capacitors offer very low ESR value. However, it provides lower capacitance density than other types. Although Tantalum capacitors have the highest capacitance density, it is important to only use types that pass the surge test for use in switching power supplies. Aluminum electrolytic capacitors have significantly higher ESR. However, it can be used in cost-sensitive applications for ripple

current rating and long term reliability considerations. Ceramic capacitors have excellent low ESR characteristics but can have a high voltage coefficient and audible piezoelectric effects. The high Q of ceramic capacitors with trace inductance can also lead to significant ringing.

### Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where T<sub>J(MAX)</sub> is the maximum junction temperature, T<sub>A</sub> is the ambient temperature, and θ<sub>JA</sub> is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance, θ<sub>JA</sub>, is layout dependent. For TSOT-23-8 (FC) package, the thermal resistance, θ<sub>JA</sub>, is 70°C/W on a standard JEDEC 51-7 four-layer thermal test board. The maximum power dissipation at T<sub>A</sub> = 25°C can be calculated by the following formula :

$$P_{D(MAX)} = (125^\circ\text{C} - 25^\circ\text{C}) / (70^\circ\text{C/W}) = 1.428\text{W for TSOT-23-8 (FC) package}$$

The maximum power dissipation depends on the operating ambient temperature for fixed T<sub>J(MAX)</sub> and thermal resistance, θ<sub>JA</sub>. The derating curve in Figure 5 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

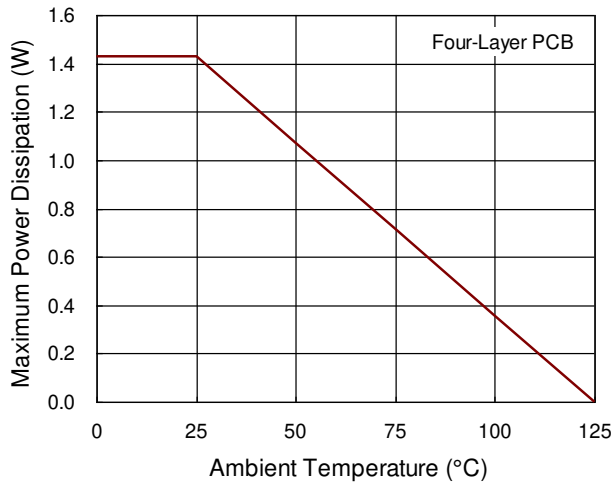


Figure 5. Derating Curve of Maximum Power Dissipation

**Layout Considerations**

For best performance of the RT6296B, the following layout guidelines must be strictly followed.

- ▶ Input capacitor must be placed as close to the IC as possible.
- ▶ SW should be connected to inductor by wide and short trace. Keep sensitive components away from this trace.
- ▶ Keep VIN, GND and SW connected to pin as wide as possible for improving thermal dissipation.

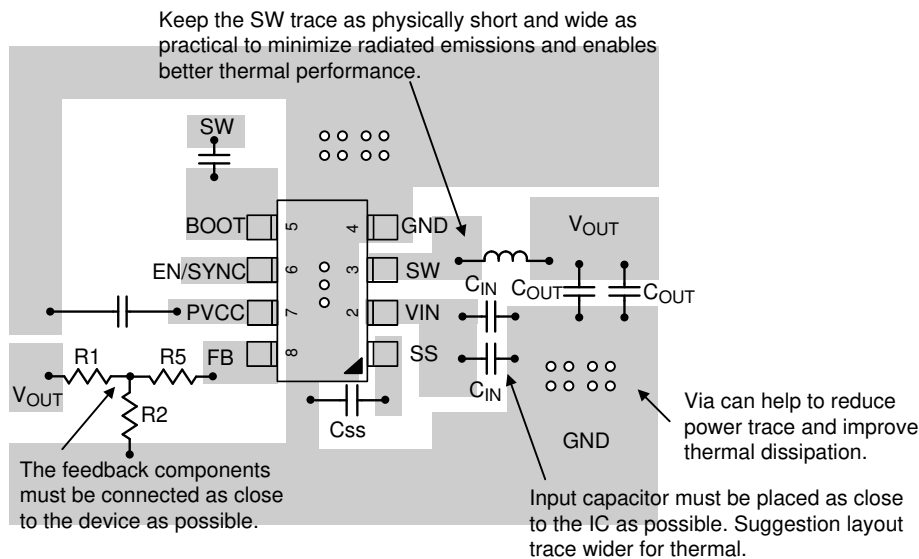
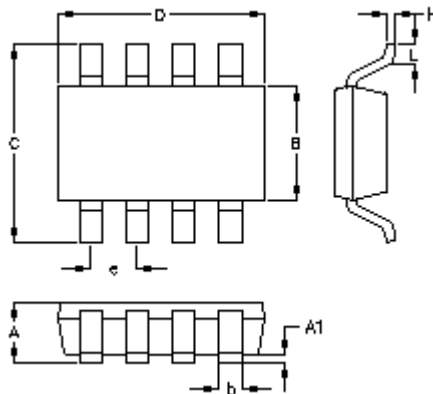


Figure 6. PCB Layout Guide

Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	1.000	0.028	0.039
A1	0.000	0.100	0.000	0.004
B	1.397	1.803	0.055	0.071
b	0.220	0.380	0.009	0.015
C	2.591	3.000	0.102	0.118
D	2.692	3.099	0.106	0.122
e	0.585	0.715	0.023	0.028
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024

TSOT-23-8 (FC) Surface Mount Package

Richtek Technology Corporation

14F, No. 8, Tai Yuen 1<sup>st</sup> Street, Chupei City  
 Hsinchu, Taiwan, R.O.C.  
 Tel: (8863)5526789

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